

10/617578

Attorney Docket No. 108298533US1
Disclosure No. 99-1116.01

In the Specification:

Please add a new section directly before the "Technical Field" on page 1 as follows:

CROSS REFERENCE TO RELATED APPLICATION

This application is a divisional application of United States Patent Application No. 09/641,498 entitled "METHODS FOR FINISHING MICROELECTRONIC DEVICE PACKAGES," filed on August 18, 2000, now Patent No. _____, which is hereby incorporated by reference in its entirety.

Please amend the first full paragraph on page ⁶ 3-16 ~~5~~ (lines 7-18) as follows:

AB
7/26/07

Figure 1 is an isometric view of a plurality of packaged microelectronic devices 100 before being processed in accordance with an embodiment of the invention. The microelectronic devices 100 can each have a microelectronic die 102, a printed circuit substrate 103 or lead frame to which each die 102 is attached, and a protective casing 110 covering each die 102. The dies 102 can be memory devices or processors that include integrated circuitry in a semiconductor substrate, or the dies 102 can be other types of microelectronic components. The printed circuit substrates 103 can each have a plurality of ball-pads 104 and traces 105 extending from the ball-pads 104. The traces 105 are coupled to corresponding bond-pads (not shown) on the die 102. The printed circuit substrates 103 shown in Figure 1 are initially part of an interposing substrate assembly 106, which may remain intact during the abrasion processes discussed below (as is evident in Figures 3-5). During Back-End-of-Line (BEOL) processing, the interposing substrate assembly 106 is cut to separate individual packaged devices 100 from one another.